Form PTO-1595 (Rev. 08/05)
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U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET

PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Veeraraghavan S. Basker (08/07/2007),
Eduard Cartier (08/08/2007),
Lili Deligianni (08/02/2007),
Rajarao Jammy (08/20/2007)
Vamsi Krishna Paruchuri (08/08/2007)

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

☒ Assignment ☐ Merger ☐ Change of Name
☐ Security Agreement ☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: International Business Machines Corporation

Internal Address:

Street Address: New Orchard Road

City: Armonk
State: New York
Country: United States of America Zip: 10504

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s): ☐ This document is being filed together with a new application.

A. Patent Application No.(s)
11/940,720

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: R. James Balls
CONNOLLY BOVE LODGE & HUTZ LLP
Internal Address: Atty. Dkt.: YOR920060833US1
Street Address: 1875 Eye Street, NW
Suite 1100

City: Washington
State: DC Zip: 20006
Phone Number: (202) 331-7111
Fax Number: (202) 293-6229
Email Address: RBalls@cblh.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $ 40.00

☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
Expiration Date

b. Deposit Account Number 50-0510
Authorized User Name R. James Balls

9. Signature:

Signature

November 19, 2007
Date

R. James Balls - 57,703
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 6

CH $40.00 500510 11940720

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ASSIGNMENT

Docket No. YOR920060833US1
(20140-00375-US1)
Page 1 of 2

Whereas, we

INVENTOR AND CITY

(1) **Veeraraghavan S. Basker** of **Schenectady,**
County of **Schenectady** and State of **New York,**
and (2) **Eduard Cartier** of **New York,**
County of **New York** and State of **New York,**
and (3) **Lili Deligianni** of **Tenafly,**
County of **Bergen** and State of **New York,**
and (4) **Rajarao Jammy** of **Hopewell Junction,**
County of **Dutchess** and State of **New York,**
and (5) **Vamsi Krishna Paruchuri** of **New York,**
County of **New York** and State of **New York,**

have invented certain improvements in

TITLE

Method and Apparatus for Electroplating on SOI and Bulk Semiconductor Wafers

DATES THAT INVENTORS SIGNED THE DECLARATION

and executed, respectively, a United States patent application therefor on

(1) Aug 7 ____, 2007, (2) ________, 2007,
(3) ________, 2007, (4) ________, 2007,
(5) ________, 2007.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

________________ on Aug 7 ____, 2007
Veeraraghavan S. Basker

________________ on ________, 2007
Eduard Cartier

________________ on ________, 2007
Lili Deligianni

________________ on ________, 2007
Rajarao Jammy

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(5) ________, 2007.

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Signed and sealed

________________ on ________, 2007
Veeraraghavan S. Basker

Eduard Cartier on 08. 08, 2007
Eduard Cartier

________________ on ________, 2007
Lili Deligianni

________________ on ________, 2007
Rajarao Jammy

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(1) __________, 2007, (2) __________, 2007,
(3) August 2, 2007, (4) __________, 2007,
(5) __________, 2007.

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Signed and sealed

____________________ on __________, 2007
Veeraraghavan S. Basker

____________________ on __________, 2007
Eduard Cartier

Harklia Deligianni on August 2 2007
Harikila Deligianni

____________________ on __________, 2007
Rajarao Jammy

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County of **Bergen** and State of **New York**,
and (4) **Rajarao Jammy** of ~~**Hopewell Junction**~~, Austin
County of ~~**Dutchess**~~ Travis and State of ~~**New York**~~, Texas
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(3) ____________, 2007, (4) 20 August, 2007,
(5) Aug 8, 2007.

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Signed and sealed

____________________ on ____________, 2007
Veeraraghavan S. Basker

____________________ on ____________, 2007
Eduard Cartier

____________________ on ____________, 2007
Lili Deligianni

____________________ on 20 August, 2007
Rajarao Jammy

ASSIGNMENT

Docket No. YOR920060833US1
(20140-00375-US1)
Page 2 of 2

P. Vamsi Krishna
Vamsi Krishna Paruchuri on August 8, 2007

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